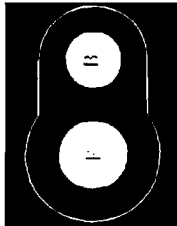
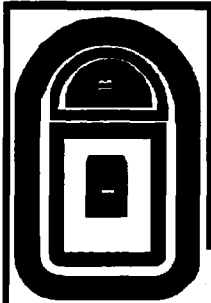
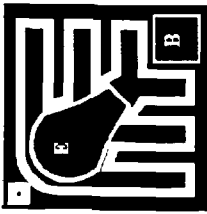


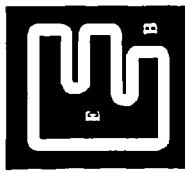
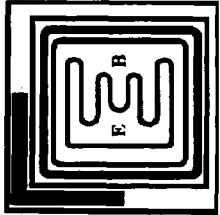
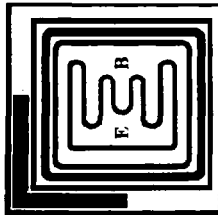
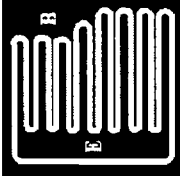
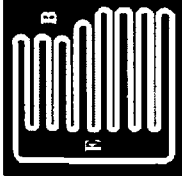
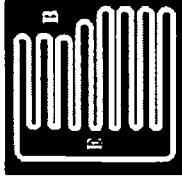
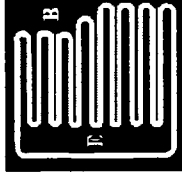
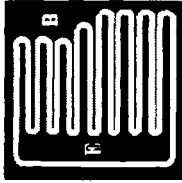
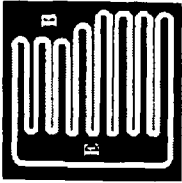
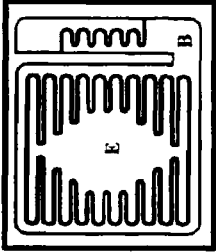
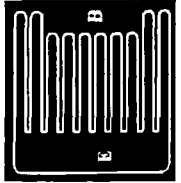
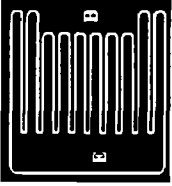
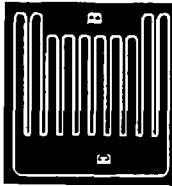
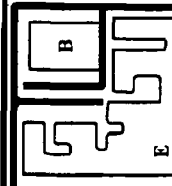
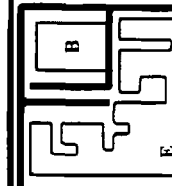


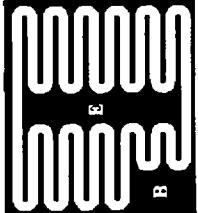
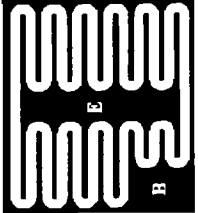
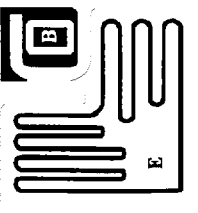
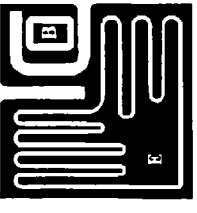
TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
1015 NPN		<ol style="list-style-type: none"> Chip size..... 15 X 19 mils ± 2 mils Chip thickness..... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 4 mils, E = 5 mils 	<p>I_C 100 mA max</p> <p>V_{CEO} 30 - 45 Vdc</p> <p>V_{EBO} 15 - 18 Vdc</p> <p>h_{FE} 50 @ 1 mA</p> <p>ft 20 MHz</p>	<p>2N2432</p> <p>2N2432A</p> <p>2N4138</p>
2020 PNP		<ol style="list-style-type: none"> Chip size..... 23 X 16 mils ± 2 mils Chip thickness..... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 3 X 5 mils, E = 5 X 4 mils 	<p>I_C 100 mA max</p> <p>V_{CEO} 35 Vdc</p> <p>V_{EBO} 40 Vdc</p> <p>h_{FE} 100 - 250 @ 1mA</p> <p>ft 15 MHz</p>	<p>2N328</p> <p>2N329</p> <p>2N2944A</p> <p>2N2945A</p> <p>2N4007</p> <p>2N4008</p> <p>2N2946A</p> <p>2N3218</p> <p>2N3219</p> <p>2N3677</p> <p>2N3910</p> <p>2N3911</p>
1020B NPN		<ol style="list-style-type: none"> Chip size..... 20 X 20 mils ± 2 mils Chip thickness..... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 5 X 5 mils, E = 6 X 4 mils 	<p>I_C 800 mA</p> <p>V_{CEO} 40 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 100 - 300 @ 150mA</p> <p>ft 300 MHz</p>	<p>2N693</p> <p>2N696</p> <p>2N718</p> <p>2N718A</p> <p>2N956</p> <p>2N1420</p> <p>2N1566</p> <p>2N2218</p> <p>2N2218A</p> <p>2N2219</p>
2020B PNP		<ol style="list-style-type: none"> Chip size..... 20 X 20 mils ± 2 mils Chip thickness..... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 5 X 5 mils, E = 6 X 4 mils 	<p>I_C 600 mA</p> <p>V_{CEO} 60 Vdc</p> <p>V_{EBO} 5.0 Vdc</p> <p>h_{FE} 100 - 300 @ 150mA</p> <p>ft 200 MHz</p>	<p>2N1132</p> <p>2N2904-A</p> <p>2N2905-A</p> <p>2N2906-A</p> <p>2N2907-A</p> <p>2N3485-A</p> <p>2N3486-A</p> <p>2N3494</p> <p>2N3638-A</p> <p>2N3644</p>

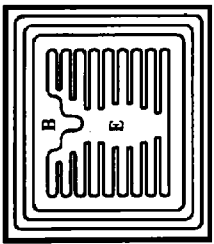
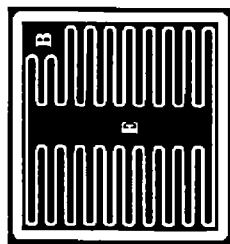
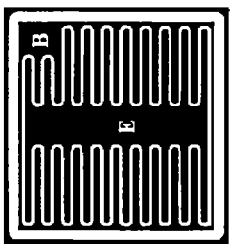
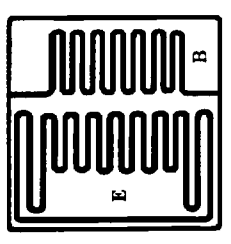
TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
1040 NPN		<ol style="list-style-type: none"> 1. Chip size..... 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 5 X 8 mils, E = 10 X 7 mils 	<p>I_C 1.0 A max</p> <p>V_{CEO} 300 - 350 Vdc</p> <p>V_{EBO} 7.0 Vdc</p> <p>h_{FE} 40 - 160 @ 20 mA</p> <p>ft 15 MHz</p>	<p>2N3439 2N3440 2N6591 2N6592 2N6593 2N6720 2N6721 2N6722 2N6723 D40P1</p> <p>D40P3 D40P5</p>
2040 PNP		<ol style="list-style-type: none"> 1. Chip size..... 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 5 X 8 mils, E = 10 X 7 mils 	<p>I_C 1.0 mA max</p> <p>V_{CEO} 200 - 300 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 30 - 150 @ 50 mA</p> <p>ft 15 MHz</p>	<p>2N5415 2N5416</p>
1040B NPN		<ol style="list-style-type: none"> 1. Chip size..... 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 6 X 8 mils, E = 6 X 4 mils 	<p>I_C 300 - 500 mA max</p> <p>V_{CEO} 150 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 100 - 300 @ 150 mA</p> <p>ft 150 MHz</p>	<p>2N3498 2N3499 2N3500 2N3501</p>
2040B PNP		<ol style="list-style-type: none"> 1. Chip size..... 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 6 X 8 mils, E = 6 X 4 mils 	<p>I_C 1.5 A max</p> <p>V_{CEO} 60 Vdc</p> <p>V_{EBO} 5.0 Vdc</p> <p>h_{FE} 30 - 120 @ 1.0 mA</p> <p>ft 180 MHz</p>	<p>2N3467 2N3468 2N3762 2N3763 2N3764 2N3765</p>


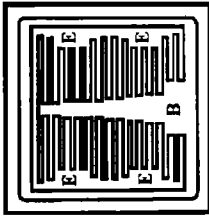
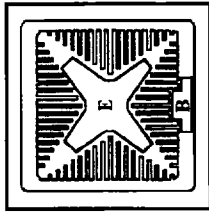
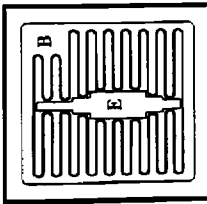
TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
1060 NPN		<ol style="list-style-type: none"> 1. Chip size..... 60 X 60 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 15 X 6 mils, E = 28 X 6 mils 	<p>I_C 1 A max</p> <p>V_{CE} 500 - 1000 Vdc</p> <p>V_{EB} 5.0 V</p> <p>h_{FE} 10 - 100</p> <p>ft 4 - 100 MHz</p>	2N5095 2N5097 2N5098 2N5099
2060 PNP		<ol style="list-style-type: none"> 1. Chip size..... 60 X 60 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 15 X 6 mils, E = 28 X 6 mils 	<p>I_C 1 A max</p> <p>V_{CE} 50 - 450 Vdc</p> <p>V_{EB} 5.0 V</p> <p>h_{FE} 10 - 100</p> <p>ft 4 - 100 MHz</p>	2N5093 2N5094 2N5096 2N5100
1075 NPN		<ol style="list-style-type: none"> 1. Chip size..... 75 X 75 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 19 X 8 mils, E = 35 X 8 mils 	<p>I_C 7.0 A max</p> <p>V_{CE} 40 - 400 Vdc</p> <p>V_{EB} 6.0 Vdc</p> <p>h_{FE} 25 - 100</p> <p>ft 1.5 - 50 MHz</p>	2N3418 2N3419 2N3420 2N3421 2N3583 2N3584 2N3585 2N3738 2N3739 2N3766 2N3767 2N3879 2N5660 2N5661 2N5662 2N5663
2075 PNP		<ol style="list-style-type: none"> 1. Chip size..... 75 X 75 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 19 X 8 mils, E = 35 X 8 mils 	<p>I_C 5.0 A max</p> <p>V_{CE} 40 - 300 Vdc</p> <p>V_{EB} 6.0 Vdc</p> <p>h_{FE} 25 - 100</p> <p>ft 3.0 - 60 MHz</p>	2N3740 2N3741 2N3867 2N3868 2N4898 2N4899 2N4900 2N5149

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
1085 NPN		<ol style="list-style-type: none"> 1. Chip size..... 85 X 85 mils \pm 2 mils 2. Chip thickness..... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 21 X 8 mils, E = 40 X 8 mils 	<p>I_C 1.5 Adc max</p> <p>V_{CEO} 55 - 100 Vdc</p> <p>V_{EBO} 12.0 Vdc</p> <p>h_{FE} 35 - 100</p> <p>ft 1.5 MHz</p>	<p>2N1479</p> <p>2N1480</p> <p>2N1481</p> <p>2N1482</p> <p>2N1483</p> <p>2N1484</p> <p>2N1485</p> <p>2N1486</p> <p>2N1701</p>
2085 PNP		<ol style="list-style-type: none"> 1. Chip size..... 85 X 85 mils \pm 2 mils 2. Chip thickness..... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 21 X 8 mils, E = 40 X 8 mils 	<p>I_C 4.0 Adc max</p> <p>V_{CEO} 80 Vdc</p> <p>V_{EBO} 7.0 Vdc</p> <p>h_{FE} 30 - 100 @ 250mA</p> <p>ft 4.0 MHz</p>	<p>2N3740</p> <p>2N3741</p> <p>2N3741A</p>
1087 NPN		<ol style="list-style-type: none"> 1. Chip size..... 87 X 100 mils \pm 2 mils 2. Chip thickness..... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B₁ = 16 X 14 mils, B₂ = 16 X 18 mils, E = 40 X 8 mils 	<p>I_C 5 Adc max</p> <p>V_{CEO} 80 - 150 Vdc</p> <p>V_{EBO} 12.0 Vdc</p> <p>h_{FE} 1000 - 10,000</p> <p>ft 50 MHz</p>	<p>2N6350</p> <p>2N6351</p> <p>2N6352</p> <p>2N6353</p>
1120 NPN		<ol style="list-style-type: none"> 1. Chip size..... 120 X 120 mils \pm 2 mils 2. Chip thickness..... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 52 X 12 mils, E = 84 X 12 mils 	<p>I_C 10 Adc max</p> <p>V_{CEO} 60 - 400 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 40 - 120</p> <p>ft 20 MHz</p>	<p>2N4150</p> <p>2N5002</p> <p>2N5004</p> <p>2N5237</p> <p>2N5238</p> <p>2N5427</p> <p>2N5428</p> <p>2N5429</p> <p>2N5430</p> <p>2N5664</p> <p>2N5665</p> <p>2N5666</p>

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
2120 PNP		<ol style="list-style-type: none"> Chip size..... 120 X 120 mils \pm 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 52 X 12 mils, E = 84 X 12 mils 	<p>I_C 5 Adc max</p> <p>V_{CE0} 80 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 30 - 240</p> <p>ft 30 MHz</p>	<p>2N5003</p> <p>2N5005</p> <p>2N6190</p> <p>2N6191</p> <p>2N6193</p>
1130 NPN		<ol style="list-style-type: none"> Chip size..... 130 X 130 mils \pm 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 52 X 12 mils, E = 84 X 12 mils 	<p>I_C 2.0 Adc max</p> <p>V_{CE0} 200 - 350 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 10 - 100</p> <p>ft 20 MHz</p>	<p>2N6211</p> <p>2N6212</p> <p>2N6213</p>
1136 NPN		<ol style="list-style-type: none"> Chip size..... 136 X 136 mils \pm 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 35 X 20 mils, E = 35 X 35 mils 	<p>I_C 8.0 Adc max</p> <p>V_{CE0} 80 Vdc</p> <p>V_{EBO} 5.0 Vdc</p> <p>h_{FE} 750 - 18,000</p> <p>ft 25 MHz</p>	<p>2N6294</p> <p>2N6295</p> <p>2N6300</p> <p>2N6301</p>
2136 PNP		<ol style="list-style-type: none"> Chip size..... 136 X 136 mils \pm 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 35 X 20 mils, E = 35 X 35 mils 	<p>I_C 8.0 Adc max</p> <p>V_{CE0} 80 Vdc</p> <p>V_{EBO} 5.0 Vdc</p> <p>h_{FE} 750 - 18,000</p> <p>ft 25 MHz</p>	<p>2N6296</p> <p>2N6297</p> <p>2N6298</p> <p>2N6299</p>

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
1170 NPN		<ol style="list-style-type: none"> 1. Chip size..... 170 X 170 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 40 X 30 mils, E = 100 X 20 mils 	<p>I_C 20 Adc max</p> <p>V_{CEO} 80 Vdc</p> <p>V_{EBO} 7.0 Vdc</p> <p>h_{FE} 20 - 150</p> <p>f_t 2.5 - 40 MHz</p>	<p>2N1724</p> <p>2N1724A</p> <p>2N1725</p> <p>2N3713</p> <p>2N3714</p> <p>2N3715</p> <p>2N3716</p> <p>2N5038</p> <p>2N5039</p>
2170 PNP		<ol style="list-style-type: none"> 1. Chip size..... 170 X 170 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 40 X 30 mils, E = 100 X 20 mils 	<p>I_C 10 Adc max</p> <p>V_{CEO} 80 Vdc</p> <p>V_{EBO} 7.0 Vdc</p> <p>h_{FE} 50 - 180</p> <p>f_t 4.0 MHz</p>	<p>2N3789</p> <p>2N3790</p> <p>2N3791</p> <p>2N3792</p>
1200 NPN		<ol style="list-style-type: none"> 1. Chip size..... 200 X 200 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 45 X 29 mils, E = 41 X 70 mils 	<p>I_C 20 Adc max</p> <p>V_{CEO} 60 - 100 Vdc</p> <p>V_{EBO} 5.0 Vdc</p> <p>h_{FE} 750 - 18,000</p> <p>f_t 4.0 MHz</p>	<p>2N6282</p> <p>2N6283</p> <p>2N6284</p> <p>2N6057</p> <p>2N6058</p> <p>2N6059</p>
2200 PNP		<ol style="list-style-type: none"> 1. Chip size..... 200 X 200 mils \pm 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 45 X 29 mils, E = 41 X 70 mils 	<p>I_C 12 Adc max</p> <p>V_{CEO} 80 - 100 Vdc</p> <p>V_{EBO} 5.0 Vdc</p> <p>h_{FE} 750 - 18,000</p> <p>f_t 4.0 MHz</p>	<p>2N6050</p> <p>2N6051</p> <p>2N6052</p>

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
1206 NPN		<ol style="list-style-type: none"> Chip size..... 206 X 206 mils ± 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 24 X 46 mils, E = 18 X 85 mils 	<p>I_C 20 Adc max</p> <p>V_{CEO} 75 - 150 Vdc</p> <p>V_{EBO} 7.0 Vdc</p> <p>h_{FE} 20 - 100</p> <p>ft 60 MHz</p>	<p>2N5038</p> <p>2N5039</p> <p>2N6354</p> <p>2N6496</p>
1230 NPN		<ol style="list-style-type: none"> Chip size..... 230 X 230 mils ± 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 30 X 38 mils, E = 33 X 156 mils 	<p>I_C 25 - 50 Adc max</p> <p>V_{CEO} 80 - 150 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 15 - 120</p> <p>ft 2 - 40 MHz</p>	<p>2N5671</p> <p>2N5672</p> <p>2N5685</p> <p>2N5686</p> <p>2N5885</p> <p>2N5886</p> <p>2N6274</p> <p>2N6277</p> <p>2N6338</p> <p>2N6339</p>
2230 PNP		<ol style="list-style-type: none"> Chip size..... 230 X 230 mils ± 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 30 X 38 mils, E = 33 X 156 mils 	<p>I_C 25 Adc max</p> <p>V_{CEO} 80 - 120 Vdc</p> <p>V_{EBO} 6.0 Vdc</p> <p>h_{FE} 20 - 120</p> <p>ft 40 MHz</p>	<p>2N5883</p> <p>2N5884</p> <p>2N6436</p> <p>2N6437</p> <p>2N6438</p>
1250 NPN		<ol style="list-style-type: none"> Chip size..... 250 X 250 mils ± 2 mils Chip thickness.... 8 - 12 mils nominal Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal Backside..... Collector Bonding pad..... B = 25 X 30 mils, E = 35 X 60 mils 	<p>I_C 20 Adc max</p> <p>V_{CEO} 400 - 550 Vdc</p> <p>V_{EBO} 2.0 Vdc</p> <p>h_{FE} 25 - 100</p> <p>ft 100 MHz</p>	<p>SVT6060</p> <p>SVT6061</p> <p>SVT6062</p>

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES
2252 PNP		<ol style="list-style-type: none"> 1. Chip size..... 250 X 250 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 25 X 30 mils, E = 35 X 60 mils 	<p>I_C 20 Adc max V_{CEO} 60 - 100 Vdc V_{EBO} 5.0 Vdc h_{FE} 750 - 18,000 ft 4.0 MHz</p>	2N6285 2N6286 2N6287
2260 PNP		<ol style="list-style-type: none"> 1. Chip size..... 260 X 260 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 53 X 100 mils, E = 42 X 22 mils 	<p>I_C 50 Adc max V_{CEO} 60 - 80 Vdc V_{EBO} 5.0 Vdc h_{FE} 15 - 60 ft 2.0 MHz</p>	2N5683 2N5684
1270B NPN		<ol style="list-style-type: none"> 1. Chip size..... 270 X 270 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 25 X 70 mils, E = 40 X 80 mils 	<p>I_C 15 Adc max V_{CEO} 300 - 450 Vdc V_{EBO} 8.0 Vdc h_{FE} 8 @ 15 A / 3 V ft 15 MHz</p>	2N6674 2N6675 2N6676 2N6677 2N6678 2N6691 2N6692 2N6693
1330 NPN		<ol style="list-style-type: none"> 1. Chip size..... 330 X 330 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal..... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal..... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside..... Collector 6. Bonding pad..... B = 35 X 67 mils, E = 52 X 120 mils 	<p>I_C 30 Adc max V_{CEO} 250 - 400 Vdc V_{EBO} 5.0 Vdc h_{FE} 30 - 150 ft 10 MHz</p>	2N6322 2N6323